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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/692,007	10/19/2000	Stephen P. DeOmellas	TEGL1082US1 SRM	TEGL1082US1 SRM 7175	
23910	7590 08/28/2002				
FLIESLER DUBB MEYER & LOVEJOY, LLP FOUR EMBARCADERO CENTER SUITE 400 SAN FRANCISCO, CA 94111			EXAMINER		
			UMEZ ERONINI, LYNETTE T		
			ART UNIT	PAPER NUMBER	
			1765	13	
			DATE MAILED: 08/28/2002	•	

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application N .	Applicant(s)			
	09/692,007	DEORNELLAS ET AL.			
Offic Action Summary	Examiner	Art Unit			
	Lynette T. Umez-Eronini	1765			
The MAILING DATE of this communication appears on the cover sheet with the correspond nce address Period for Reply					
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).					
Status					
1) Responsive to communication(s) filed on					
, <u> </u>	s action is non-final.				
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213. Disposition of Claims					
4) Claim(s) 1-49 is/are pending in the application.					
4a) Of the above claim(s) <u>1-9</u> is/are withdrawn from consideration.					
5) Claim(s) is/are allowed.					
6)⊠ Claim(s) <u>10-49</u> is/are rejected.					
7) Claim(s) is/are objected to.					
8) Claim(s) are subject to restriction and/or	election requirement				
Application Papers					
9)☐ The specification is objected to by the Examiner.					
10) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.					
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).					
11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.					
If approved, corrected drawings are required in reply to this Office action.					
12)☐ The oath or declaration is objected to by the Examiner.					
Pri rity under 35 U.S.C. §§ 119 and 120					
13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).					
a) ☐ All b) ☐ Some * c) ☐ None of:					
1. Certified copies of the priority documents have been received.					
2. Certified copies of the priority documents have been received in Application No					
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 					
14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).					
 a) ☐ The translation of the foreign language provisional application has been received. 15)☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121. 					
Attachment(s)					
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of Informal	y (PTO-413) Paper No(s) Patent Application (PTO-152)			
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DETAILED ACTION

Claim Rej ctions - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 10-49 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fullowan et al. (US 5,176,792) in view of Moslehi (US 5,192,849).

Fullowan teaches a method for etching a pattern on a workpiece including the steps of:

selecting a workpiece with a hard mask deposited over a (tungsten) layer to be etched, which hard mask is comprised of a (titanium mask 12) reactive metal (column 1, lines 51-54 and column 2, lines 39-44). Since Fullowan uses the same hard mask material as that of the present invention, then using Fullowan's hard mask layer would inherently result in said hard mask having a low reactivity to the etch chemistry of an etch process, as in claim 13 and said hard mask has a low sputter yield and a low reactivity to etch chemistry of an etch process, as in claims 22 and 28;

plasma etching the mask workpiece to selectively remove the unmasked tungsten and performing the etching in a plasma etcher that is water-cooled to room temperature (column 2, lines 55-61), reads on,

processing the workpiece in a reactor using an etch step and exposing the hard mask to the etch.

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Fullowan differs in failing to teach providing energy to the reactor, in claims 10, 13, 22, 25, 26, 28, 29, 30, 34.

Moslehi teaches conventional RF plasma chucks can usually operate in the range of 0°C to 200°C (column 3, lines 8-11); the chuck can experience temperatures operating in the range of -150°C to 750°C (column 6, lines 48-51); the RF chuck is compatible with single-wafer plasma processing reactors and has the advantage of improving the etch rate in reactive-ion etching of polysilicon, aluminum, oxides, and polyimides (column 5, lines 12-14 and 22-26). Since Moslehi operates a chuck that is used in reactive ion etching the same material (i.e. aluminum) as a hard mask as claimed in the present invention and at temperatures that overlap that of the present invention, then using Moslehi method of operating a RF plasma chuck reads on providing energy to the reactor and would inherently increase a rate of oxidation of the hard mask in order to slow down the rate of erosion of the hard mask.

It would have been obvious to one having ordinary skill in the art at the time of the claimed invention to modify Fullowan by using Moslehi's method of providing energy to the reactor for the purpose of improving reactive ion etch rate of the material being etched.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lynette T. Umez-Eronini whose telephone number is 703-306-9074. The examiner is normally unavailable on the First Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Benjamin Utech can be reached on 703-308-3836. The fax phone numbers

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for the organization where this application or proceeding is assigned are 703-972-9310 for regular communications and 703-972-9311 for After Final communications.

Itue August 22, 2002

> ROBERT KUNEMUND PRIMARY EXAMINER